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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China











DMMT3904W

40V MATCHED PAIR NPN SMALL SIGNAL TRANSISTOR IN SOT363

Features

- BVceo > 40V
- I_C = 200mA high Collector Current
- Pair of NPN transistors that are intrinsically matched (Note 1)
- 2% Matching on Current Gain (hFE)
- 2mV Matching on Base-Emitter Voltage (V_{BE})
- Fully internally isolated in a small surface mount package
- Totally Lead-Free & Fully RoHS Compliant (Notes 2 & 3)
- Halogen and Antimony Free. "Green" Device (Note 4)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 5)

Mechanical Data

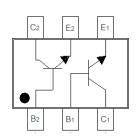
- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Finish. Solderable per MIL-STD-202, Method 208 ³
- Weight: 0.006 grams (approximate)

Applications

- Current mirrors
- Differential and instrumentation amplifiers
- Comparators



Top View



Device Schematic and Pin-Out Top View

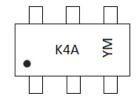
Ordering Information (Note 4 & 5)

Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DMMT3904W-7-F	AEC-Q101	K4A	7	8	3,000
DMMT3904WQ-7-F	Automotive	K4A	7	8	3,000

Notes:

- 1. Intrinsically matched pair as this is built with adjacent die from the same wafer.
- 2. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 3. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 4. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 5. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_compliance_definitions/.
- 6. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



K4A = Product Type Marking Code YM = Date Code Marking Y = Year (ex: B = 2014) M = Month (ex: 2 = February)

Date Code Key

Year	2010	201	11	2012	20	013	2014	2	2015	2016		2017
Code	Х	Y		Z		A	В		С	D		E
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Absolute Maximum Ratings (@T_A = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	60	V
Collector-Emitter Voltage	V_{CEO}	40	V
Emitter-Base Voltage	V_{EBO}	6.0	V
Collector Current	Ic	200	mA

$\textbf{Thermal Characteristics - Total Device} \ (@T_A = +25 ^{\circ}\text{C unless otherwise specified.})$

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 7) Total Device	P_{D}	200	mW
Thermal Resistance, Junction to Ambient (Note 7)	$R_{ hetaJA}$	625	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

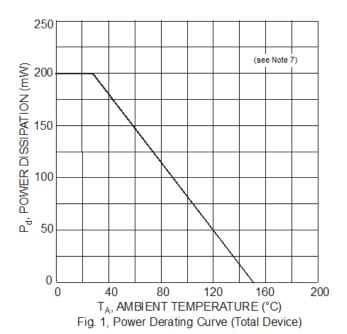
ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Note:

8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics - Total Device



^{7.} For a device mounted on minimum recommended pad layout with 1oz copper that is on a single-sided 1.6mm FR4 PCB; the device is measured under still air conditions whilst operating in a steady-state.



Electrical Characteristics (@TA = +25°C unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS				I.			
Collector-Base Breakdown Voltage	BV _{CBO}	60	_	_	V	I _C = 100μA, I _E = 0	
Collector-Emitter Breakdown Voltage(Note 9)	BV _{CEO}	40	_	_	V	I _C = 1.0mA, I _B = 0	
Emitter-Base Breakdown Voltage	BV _{EBO}	6.0	_	_	V	$I_E = 100 \mu A, I_C = 0$	
Collector Cutoff Current	I _{CEX}	_	_	50	nA	V _{CE} = 30V, V _{EB(OFF)} = 3.0V	
Base Cutoff Current	I _{BL}	_	_	50	nA	V _{CE} = 30V, V _{EB(OFF)} = 3.0V	
ON CHARACTERISTICS (Note 9)	•		•	•	•		
DC Current Gain	hfE	40 70 100 60 30	_	 300 	_	$I_{C} = 100\mu A, V_{CE} = 1.0V$ $I_{C} = 1.0m A, V_{CE} = 1.0V$ $I_{C} = 10m A, V_{CE} = 1.0V$ $I_{C} = 50m A, V_{CE} = 1.0V$ $I_{C} = 100m A, V_{CE} = 1.0V$	
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	_	_	200 300	mV	$I_C = 10mA$, $I_B = 1.0mA$ $I_C = 50mA$, $I_B = 5.0mA$	
Base-Emitter Saturation Voltage	V _{BE(SAT)}	0.65	_	850 950	mV	$I_C = 10$ mA, $I_B = 1.0$ mA $I_C = 50$ mA, $I_B = 5.0$ mA	
MATCHING CHARACTERISTICS							
DC Current Gain Matching (Note 10)	h _{FE1} / h _{FE2}		1	2	%	$I_C = 2mA$, $V_{CE} = 5V$	
Base-Emitter Voltage Matching (Note 11)	V _{BE1} - V _{BE2}		1	2	mV	$I_C = 2mA$, $V_{CE} = 5V$	
Collector-Emitter Saturation Voltage (Note 10)	V _{CE(SAT)1} / V _{CE(SAT)2}	_	1	2	%	I _C = 10mA, I _B = 1.0mA	
Base-Emitter Saturation Voltage (Note 10)	V _{BE(SAT)1} / V _{BE(SAT)2}	_	1	2	%	I _C = 10mA, I _B = 1.0mA	
SMALL SIGNAL CHARACTERISTICS							
Output Capacitance	C_{obo}		_	4.0	pF	$V_{CB} = 5.0V$, $f = 1.0MHz$, $I_E = 0$	
Input Capacitance	C _{ibo}		—	8.0	pF	$V_{EB} = 0.5V$, $f = 1.0MHz$, $I_{C} = 0$	
Input Impedance	h _{ie}	1.0	_	10	kΩ		
Voltage Feedback Ratio	h _{re}	0.5	_	8	x 10 ⁻⁴	$V_{CE} = 10V, I_{C} = 1.0 \text{mA},$	
Small Signal Current Gain	h _{fe}	100	_	400	_	f = 1.0kHz	
Output Admittance	h _{oe}	1.0	_	40	μS		
Current Gain-Bandwidth Product	f⊤	300	_	_	MHz	V _{CE} = 20V, I _C = 10mA, f = 100MHz	
Noise Figure	NF	_	_	5.0	dB	$V_{CE} = 5.0V$, $I_{C} = 100\mu A$, $R_{S} = 1.0k\Omega$, $f = 1.0kHz$	
SWITCHING CHARACTERISTICS							
Delay Time	t _d		_	35	ns	$V_{CC} = 3.0V, I_{C} = 10mA,$	
Rise Time	t _r		_	35	ns	$V_{BE(off)} = -0.5V, I_{B1} = 1.0mA$	
Storage Time	ts		_	200	ns	V _{CC} = 3.0V, I _C = 10mA,	
Fall Time	t _f	_		50	ns	$I_{B1} = I_{B2} = 1.0 \text{mA}$	

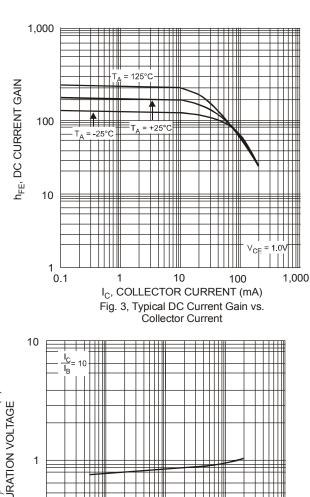
Note:

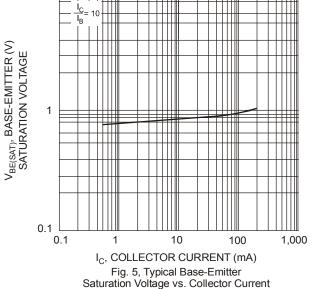
^{9.} Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%. 10. Is the ratio of one transistor compared to the other transistor.

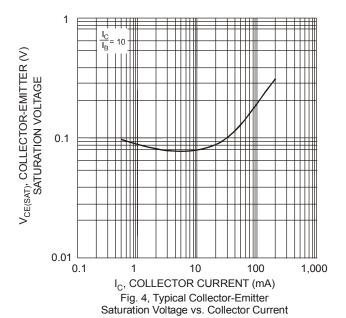
^{11.} V_{BE1} - V_{BE2} is the absolute difference of one transistor compared to the other transistor.



Typical Electrical Characteristics (@T_A = +25°C unless otherwise specified.)





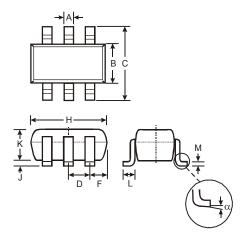


Collector-Base Voltage



Package Outline Dimensions

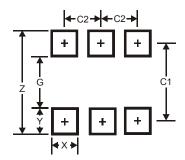
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



	SOT363						
Dim	Min	Max	Тур				
A	0.10	0.30	0.25				
В	1.15	1.35	1.30				
U	2.00	2.20	2.10				
D		0.65 Typ					
F	0.40 0.45 0.42						
Н	1.80	2.20	2.15				
7	0	0.10	0.05				
K	0.90	1.00	1.00				
L	0.25	0.40	0.30				
М	0.10	0.22	0.11				
α	0°	8°	-				
All Dimensions in mm							

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Y	0.6
C1	1.9
C2	0.65



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